Contribution ID: **65** Type: **Oral**

Hybrid pixel modules and R&D on compact modules

Monday, 20 February 2017 15:20 (20 minutes)

For the High-Luminosity upgrade of the LHC, a new pixel detector is foreseen for the ATLAS experiment. Currently, the prototyping phase is ongoing to build various detector components. The standard hybrid pixel modules consisting of a silicon pixel sensor and front-end electronics connected via bump-bonging are widely used. Prototypes with p-type sensors are built and tested.

In addition, the R&D activity deploying an alternative module assembly step, the concept using through-silicon-vias and laser soldering will be shown. Using modified components of standard modules first trials of TSV modules are discussed.

TRACK

Planar Sensors

Authors: KUEHN, Susanne (CERN); BATES, Richard (University of Glasgow (GB)); PERNEGGER, Heinz (CERN); HUEGGING, Fabian (University of Bonn)

Presenter: KUEHN, Susanne (CERN)

Session Classification: Session 2: Planar Sensors (1)